

Single Channel

Silicon ESD Protector Overvoltage Protection Device PRODUCT: SESD0201X1UN-0030-088

DOCUMENT: SCD28654

REV LETTER: B

REV DATE: MARCH 17, 2014

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Specification Status: RELEASED

BENEFITS

- Low capacitance; provides low insertion loss for high speed data signals
- Small size ESD protection diodes for high speed data signals (0201 size devices)
- Helps protect electronic circuits against damage from Electrostatic Discharge (ESD), surge and cable discharge events
- Assists equipment to pass IEC61000-4-2, level 4 testing

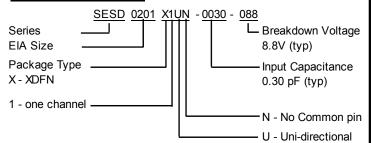
FEATURES

- Low capacitance: 0.30 pF (typ)
- Low leakage current: 25nA @ 5V (typ)
- Low clamping voltage: +13.0V(typ) @ $(tp=8x20\mu s, Ipp=2.5A)$
- ESD maximum rating per IEC61000-4-2 standard:
 - ±22kV contact discharge
 - ±22kV air discharge
- Surge: 2.5A (max) @ (tp=8x20µs) per IEC61000-4-5
- Small size and low profile: XDFN packages

APPLICATIONS

- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Ultra-high speed data lines
- USB 3.0/2.0, HDMI 1.3/1.4, DisplayPort, V-by-One HS, and LVDS interfaces
- Applications requiring high ESD performance in small packages

PART NUMBERING



PART MARKING



MATERIALS INFORMATION

RoHS Compliant ELV Compliant Halogen Free * Lead Free



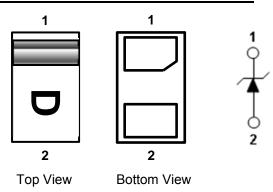






* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm SESD devices meet MSL-1 Requirements DFN case epoxy meets UL 94 V-0

PIN CONFIGURATION AND SCHEMATIC



* Drawing not to scale



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DEVICE MAXIMUM RATING

ESD Withstand ⁽¹⁾ (IEC 61000-4-2, level 4)		Tempe	Peak Current (tp=8x20μs)	
Contact (kV)	Air (kV)	Operating (°C)	Storage (°C)	lpp (A)
± 22	± 22	-55 to +125	-55 to +150	2.5

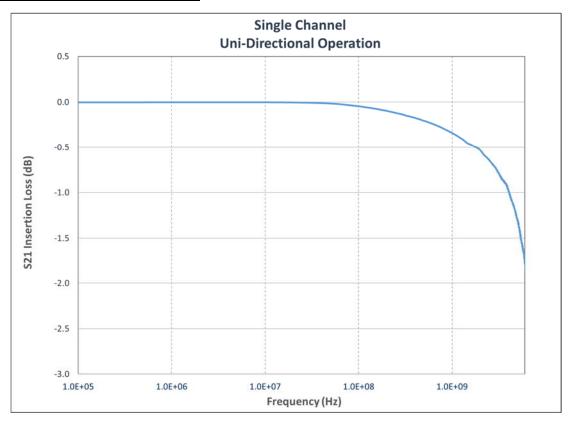
- (1) 22kV @ 10 pulses; 20kV @ 100 pulses; 8kV @ 1,000 pulses (under IEC6100-4-2)
- Device maximum rating @ T = 25°C, unless otherwise specified
- Caution: Stress exceeding Device Maximum Ratings may damage the device
 Prolonged exposure to stresses above the recommended operating conditions may affect device reliability

DEVICE ELECTRICAL CHARACTERISTICS

Input Capacitance @ V _R = 0V, f = 3GHz (pF)	Breakdown Voltage (V) V _{BR} @ I _T =1mA (V)	Reverse Working Voltage (V)	Reverse Leakage Current (A) I _L @ V _{RWM} =5.0V (nA)	Clamping Voltage V _{CL} @ Ipp=2.5A (V)
Тур	Тур	Тур	Тур	Тур
0.30	+8.80 / -0.80	7.00	25.0	+13.0

• All device electrical characteristics @ T = 25°C, unless otherwise specified

FIGURE 1. INSERTION LOSS DIAGRAM





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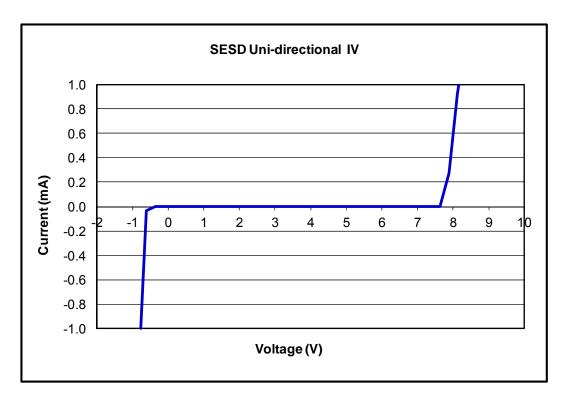
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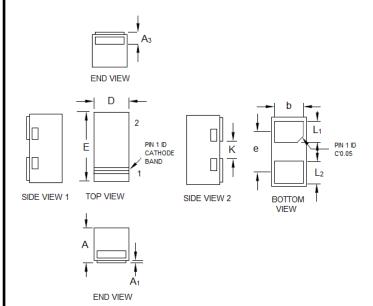
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FIGURE 2. DEVICE IV CURVE



DEVICE DIMENSIONS



	SESD0201						
	Millimeters (mm)			Inches (in)			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.28	0.30	0.32	0.011	0.012	0.013	
A ₁	0	-	0.05	0	-	0.002	
A_3	0.102 ref.			0.004 ref.			
D	0.25	0.30	0.35	0.010	0.012	0.014	
E	0.55	0.60	0.65	0.022	0.024	0.026	
K	0.11	0.17	0.22	0.004	0.007	0.009	
b	0.20	0.25	0.30	0.008	0.010	0.012	
L ₁	0.13	0.18	0.23	0.005	0.008	0.009	
L ₂	0.14	0.19	0.24	0.006	0.007	0.009	
е	0.356 BSC			0	.014 BS	С	

BSC – Basic Spacing between Centers



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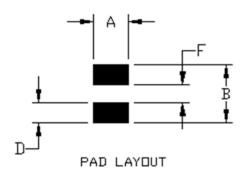
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RECOMMENDED LANDING PATTERN:

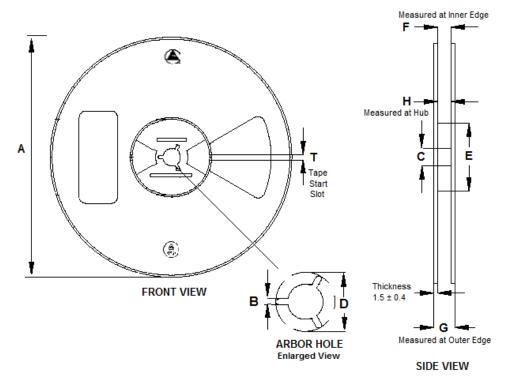


SESD Landing Pad Layout				
0201 Package				
Symbol Milimeters Inches				
Symbol	(mm)	(in)		
Α	0.32	0.013		
В	0.62	0.024		
D	0.24	0.009		
F	0.14	0.006		

PACKAGING

Packaging	Tape & Reel	Standard Box	
SESD0201X1UN-0030-088	15,000	75,000	

REEL DIMENSIONS



Dimensions	Α	В	С	D	E	F	G	Н
(mm)	180 ± 2.00	1.50 (min)	13.10 ± 0.20	20.20 (min)	60 ± 1.00	8.75 ± 1.00	11.6 ± 1.00	9.4 (max)



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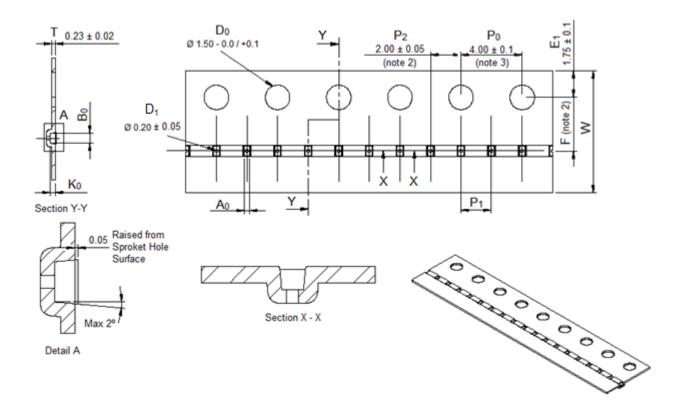
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CARRIER TAPE DIMENSIONS



A 0	0.36 ± 0.03
B ₀	0.66 ± 0.03
K ₀	0.33 ± 0.03
F	3.50 ± 0.05
P ₁	2.00 ± 0.10
W	8.00 ± 0.10

- Note 1. All dimensions in mm
- Note 2. Measured from centerline of pocket to centerline of sprocket hole
- Note 3. Cumulative tolerance of 10 sprocket holes is \pm 0.20
- Note 4. Tolerances unless noted ± 0.20



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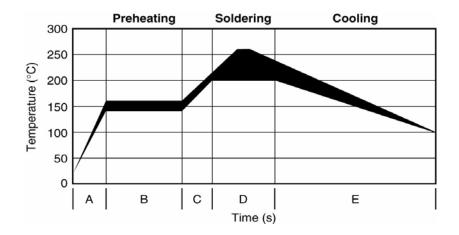
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SOLDER REFLOW RECOMMENDATION

Α	Temperature	From ambient to	30s to 60s	
_ ^	ramp up 1	Preheating temperature	303 10 003	
В	Preheating	140°C - 160°C	60s to 120s	
С	Temperature	From Preheating to Main	20s to 40s	
	ramp up 2	heating temperature	203 10 405	
D		at 200°C	60s ~ 70s	
	Main heating	at 220°C	50s ~ 60s	
	Main nealing	at 240°C	30s ~ 40s	
		at 260°C	5s ~ 10s	
F	Cooling	From main heating	4°C/s (max)	
	Cooling	temperature to 100°C	4 C/S (IIIax)	

FIGURE 3. REFLOW PROFILE



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